

Data sheet Product ICK BGA 37 x 37 x 10



Heatsinks and active heatsinks for processors > Heatsinks for BGAs
37 x 37 x 10 mm, for IC design BGA and others

Features

| | |
|------------------------------|-------------------------------------------------------------------------------------------------------------|
| way of fixation: | <ul style="list-style-type: none"> • therm. conductive foil • therm. cond. adhesive |
| socket: | universal |
| suitable for processor type: | universal |
| width: | 37 mm |
| height: | 10 mm |
| plate thickness: | 1.8 mm |
| length: | 37 mm |
| thermal resistance: | 14 - 5 K/W |
| dissipation loss: | 10.5 W |
| surface: | black anodised |

Technical Drawing

